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XINBOLE

Product Specification

SM6442D1RL

N-Channel Enhancement Mode MOSFET

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Descriptions

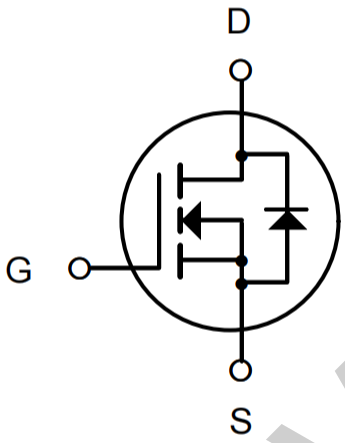
The SM6442D1RL uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

Features

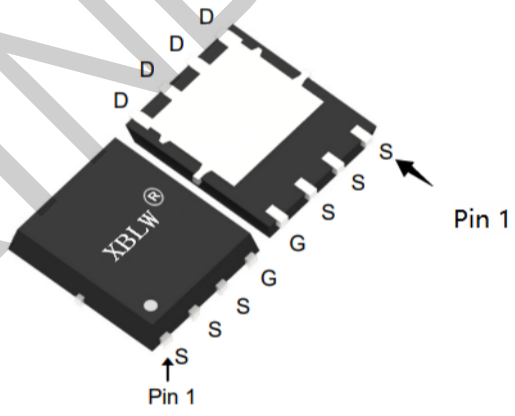
- V_{DS} = 40V,I_D = 70A
- $R_{DS(ON)}$ <8.5mΩ @ V_{GS}= 10V

Applications

- Battery protection
- Load switch
- Uninterruptible power supply



N-Channel MOSFET



DFN5X6-8L

Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
SM6442D1RL	DFN5X6-8L	SM6442D1RL	Tape	5000Pcs/Reel

Absolute Maximum Ratings (T_C=25 ℃ unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@T_C=25℃	Continuous Drain Current, V_{GS} @ 10V[1]	70	A
I_D@T_C=100℃	Continuous Drain Current, V_{GS} @ 10V[1]	44	A
I_{DM}	Pulsed Drain Current[2]	280	A
EAS	Single Pulse Avalanche Energy[3]	76	mJ
P_D@T_C=25℃	Total Power Dissipation[4]	72.3	W
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃
$R_{\theta JA}$	Thermal Resistance Junction-ambient (Steady State)[1]	62	℃/W
$R_{\theta JC}$	Thermal Resistance Junction-Case[1]	1.73	℃/W

Electrical Characteristics (Ta=25℃ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	40	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V , I_D=10A	---	6.5	8.5	mΩ
		V_{GS}=4.5V , I_D=5A	---	10	15	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1.0	1.7	3	V
I_{DSS}	Drain-Source Leakage Current	V_{DS}=32V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=32V , V_{GS}=0V , T_J=55℃	---	---	5	
I_{GSS}	Gate-Source Leakage Current	V_{GS}= ±20V , V_{DS}=0V	---	---	±100	nA
gfs	Forward Transconductance	V_{DS}=10V , I_D=5A	---	13	---	S
Q_g	Total Gate Charge (4.5V)	V_{DS}=20V , V_{GS}=10V , I_D=10A	---	20	---	nC
Q_{gs}	Gate-Source Charge		---	2.8	---	
Q_{gd}	Gate-Drain Charge		---	5.1	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=15V , V_{GS}=10V R_G=3.3Ω I_D=1A	---	13.2	---	ns
T_r	Rise Time		---	2.2	---	
$T_{d(off)}$	Turn-Off Delay Time		---	72	---	
T_f	Fall Time		---	4.5	---	
C_{iss}	Input Capacitance	V_{DS}=25V , V_{GS}=0V , f=1MHz	---	1278	---	pF
C_{oss}	Output Capacitance		---	135	---	
C_{rss}	Reverse Transfer Capacitance		---	87	---	
I_S	Continuous Source Current[1,5]	V_G=V_D=0V , Force Current	---	---	70	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1	V

Note :

1.The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2% .

3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=47A .

4.The power dissipation is limited by 150℃ junction temperature .

5.The data is theoretically the same as I_D and I_{DM}, in real applications , should be limited by total power dissipation.

Typical Characteristics

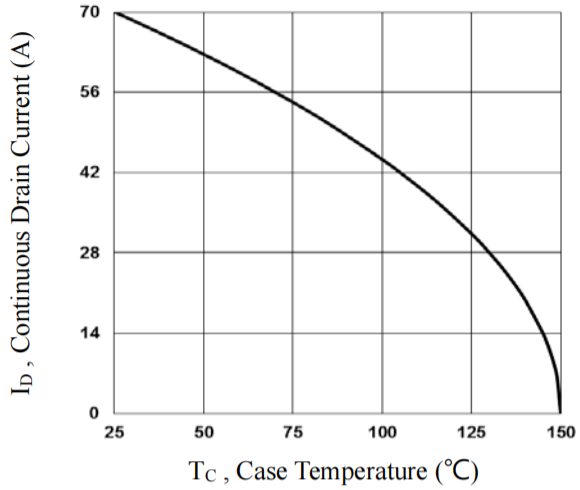


Fig 1. Continuous Drain Current vs. T_C

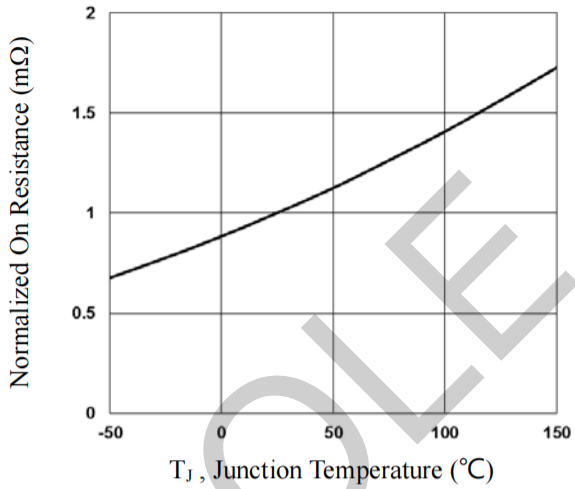


Fig 2.Normalized RDSON vs. T_J

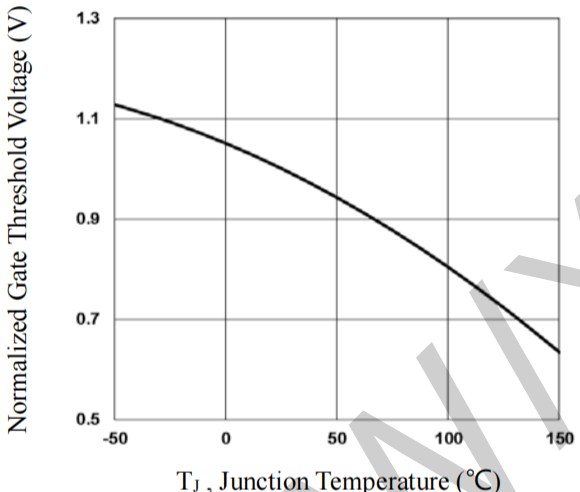


Fig 3. Normalized Vth vs. T_J

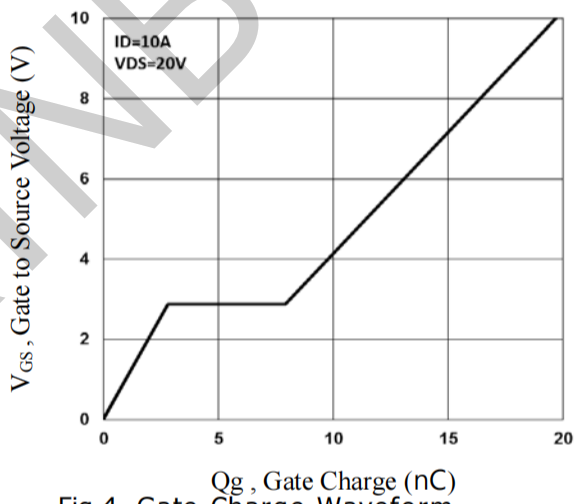


Fig 4. Gate Charge Waveform

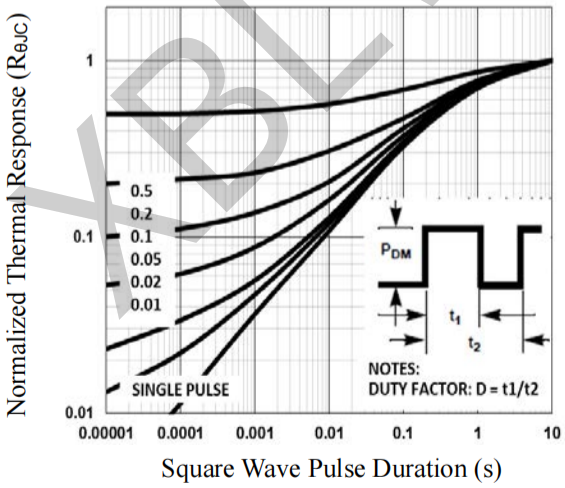


Fig 5. Normalized Transient Impedance

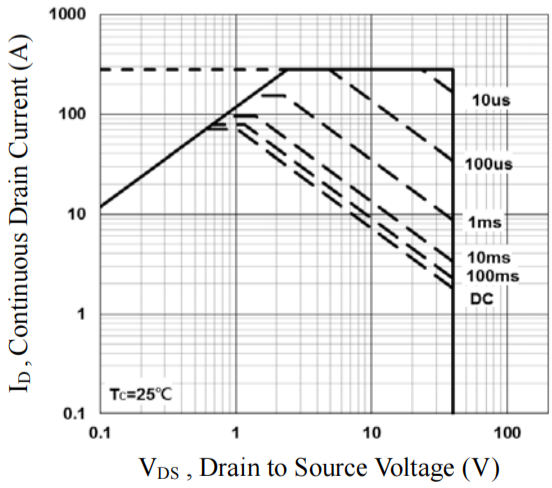


Fig 6. Maximum Safe Operation Area

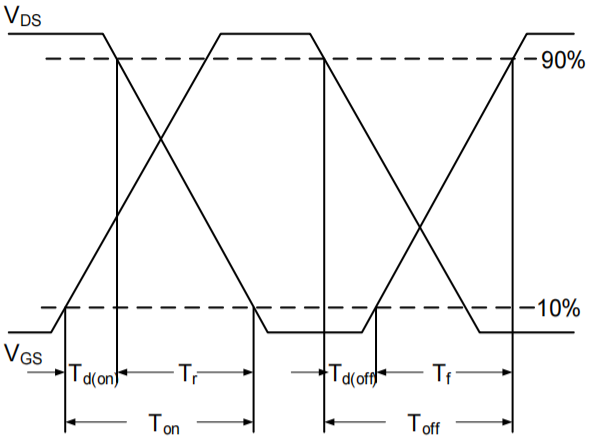


Fig 7. Switching Time Waveform

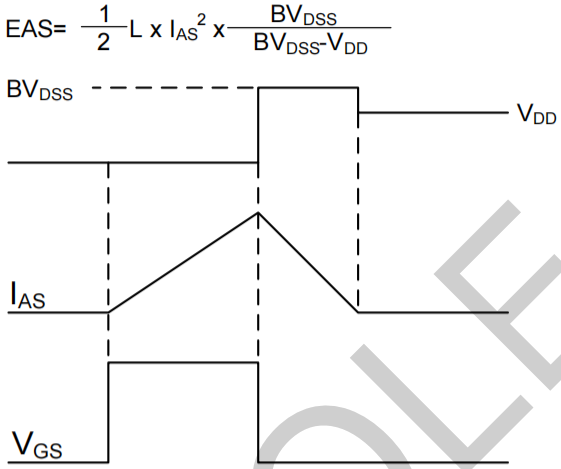
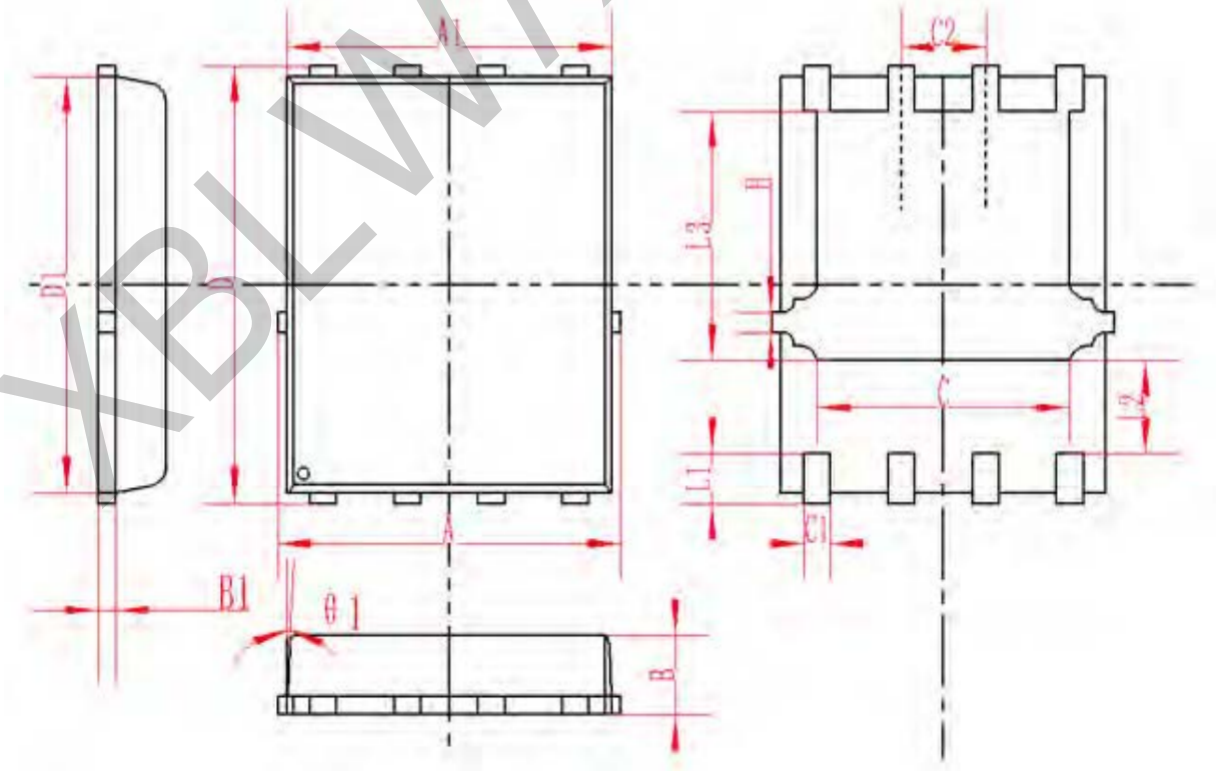


Fig 8. EAS Waveform

Package Information

DFN5X6-8L

SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.95	5	5.05	0.195	0.197	0.199
A1	4.82	4.9	4.98	0.190	0.193	0.196
D	5.98	6	6.02	0.235	0.236	0.237
D1	5.67	5.75	5.83	0.223	0.226	0.230
B	0.9	0.95	1	0.035	0.037	0.039
B1	0.254REF			0.010REF		
C	3.95	4	4.05	0.156	0.157	0.159
C1	0.35	0.4	0.45	0.014	0.016	0.018
C2	1.27TYP			0.5TYP		
θ1	8°	10°	12°	8°	10°	12°
L1	0.63	0.64	0.65	0.025	0.025	0.026
L2	1.2	1.3	1.4	0.047	0.051	0.055
L3	3.415	3.42	3.425	0.134	0.135	0.135
H	0.24	0.25	0.26	0.009	0.010	0.010



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